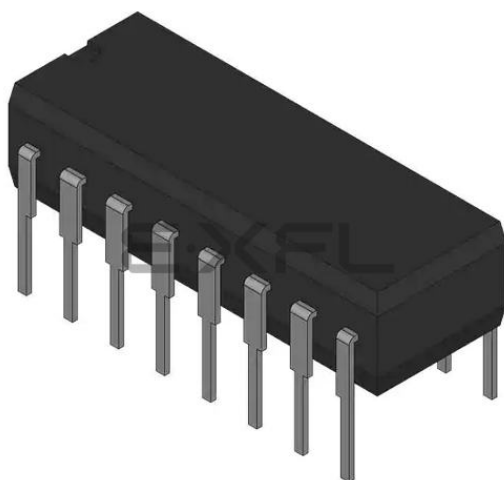




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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc68hc908qy1mpe

Revision History

The following revision history table summarizes changes contained in this document. For your convenience, the page number designators have been linked to the appropriate location.

Revision History (Sheet 1 of 3)

Date	Revision Level	Description	Page Number(s)
September, 2002	N/A	Initial release	N/A
December, 2002	0.1	1.2 Features — Added 8-pin dual flat no lead (DFN) packages to features list.	19
		Figure 1-2. MCU Pin Assignments — Figure updated to include DFN packages.	21
		Figure 2-1. Memory Map — Clarified illegal address and unimplemented memory.	27
		Figure 2-2. Control, Status, and Data Registers — Corrected bit definitions for Port A Data Register (PTA) and Data Direction Register A (DDRA).	27
		Table 13-3. Interrupt Sources — Corrected vector addresses for keyboard interrupt and ADC conversion complete interrupt.	118
		Chapter 13 System Integration Module (SIM) — Removed reference to break status register as it is duplicated in break module.	113
		11.3.1 Internal Oscillator and 11.3.1.1 Internal Oscillator Trimming — Clarified oscillator trim option ordering information and what to expect with untrimmed device.	92
		Figure 11-5. Oscillator Trim Register (OSCTRIM) — Bit 1 designation corrected.	98
		Figure 15-13. Monitor Mode Circuit (Internal Clock, No High Voltage) — Diagram updated for clarity.	150
		Figure 12-1. I/O Port Register Summary — Corrected bit definitions for PTA7, DDRA7, and DDRA6.	99
		Figure 12-2. Port A Data Register (PTA) — Corrected bit definition for PTA7.	100
		Figure 12-3. Data Direction Register A (DDRA) — Corrected bit definitions for DDRA7 and DDRA6.	101
		Figure 12-6. Port B Data Register (PTB) — Corrected bit definition for PTB1	103
		Chapter 9 Keyboard Interrupt Module (KBI) — Section reworked after deletion of auto wakeup for clarity.	83
		Chapter 4 Auto Wakeup Module (AWU) — New section added for clarity.	49
		Figure 10-1. LVI Module Block Diagram — Corrected LVI stop representation.	87
		Chapter 16 Electrical Specifications — Extensive changes made to electrical specifications.	169
		17.5 8-Pin Dual Flat No Lead (DFN) Package (Case #1452) — Added case outline drawing for DFN package.	177
		Chapter 17 Ordering Information and Mechanical Specifications — Added ordering information for DFN package.	185
January, 2003	0.2	4.2 Features — Corrected third bulleted item.	49

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Memory

Addr.	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
\$0006 ↓ \$000A	Unimplemented								
\$000B	Port A Input Pullup Enable Register (PTAPUE) See page 99.	Read: OSC2EN	0	PTAPUE5	PTAPUE4	PTAPUE3	PTAPUE2	PTAPUE1	PTAPUE0
		Write:							
		Reset:	0	0	0	0	0	0	0
\$000C	Port B Input Pullup Enable Register (PTBPUE) See page 102.	Read: PTBPUE7	PTBPUE6	PTBPUE5	PTBPUE4	PTBPUE3	PTBPUE2	PTBPUE1	PTBPUE0
		Write:							
		Reset:	0	0	0	0	0	0	0
\$000D ↓ \$0019	Unimplemented								
\$001A	Keyboard Status and Control Register (KBSCR) See page 83.	Read: 0	0	0	0	KEYF	0	IMASKK	MODEK
		Write:					ACKK		
		Reset:	0	0	0	0	0	0	0
\$001B	Keyboard Interrupt Enable Register (KBIER) See page 84.	Read: 0	AWUIE	KBIE5	KBIE4	KBIE3	KBIE2	KBIE1	KBIE0
		Write:							
		Reset:	0	0	0	0	0	0	0
\$001C	Unimplemented								
\$001D	IRQ Status and Control Register (INTSCR) See page 77.	Read: 0	0	0	0	IRQF	0	IMASK	MODE
		Write:					ACK		
		Reset:	0	0	0	0	0	0	0
\$001E	Configuration Register 2 (CONFIG2) ⁽¹⁾ See page 53.	Read: IRQPUD	IRQEN	R	OSCOPT1	OSCOPT0	R	R	RSTEN
		Write:							
		Reset:	0	0	0	0	0	0	0 ⁽²⁾
		1. One-time writable register after each reset. 2. RSTEN reset to 0 by a power-on reset (POR) only.							
\$001F	Configuration Register 1 (CONFIG1) ⁽¹⁾ See page 54.	Read: COPRS	LVISTOP	LVISTD	LVIPWRD	LVI5OR3	SSREC	STOP	COPD
		Write:							
		Reset:	0	0	0	0	0 ⁽²⁾	0	0
		1. One-time writable register after each reset. 2. LVI5OR3 reset to 0 by a power-on reset (POR) only.							
\$0020	TIM Status and Control Register (TSC) See page 127.	Read: TOF	TOIE	TSTOP	0	0	PS2	PS1	PS0
		Write:	0		TRST				
		Reset:	0	0	1	0	0	0	0
\$0021	TIM Counter Register High (TCNTH) See page 128.	Read: Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:							
		Reset:	0	0	0	0	0	0	0
		= Unimplemented R = Reserved U = Unaffected							

Figure 2-2. Control, Status, and Data Registers (Sheet 2 of 5)

3.3.2 Voltage Conversion

When the input voltage to the ADC equals V_{DD} , the ADC converts the signal to \$FF (full scale). If the input voltage equals V_{SS} , the ADC converts it to \$00. Input voltages between V_{DD} and V_{SS} are a straight-line linear conversion. All other input voltages will result in \$FF if greater than V_{DD} and \$00 if less than V_{SS} .

NOTE

Input voltage should not exceed the analog supply voltages.

3.3.3 Conversion Time

Sixteen ADC internal clocks are required to perform one conversion. The ADC starts a conversion on the first rising edge of the ADC internal clock immediately following a write to the ADSCR. If the ADC internal clock is selected to run at 1 MHz, then one conversion will take 16 μ s to complete. With a 1-MHz ADC internal clock the maximum sample rate is 62.5 kHz.

$$\text{Conversion Time} = \frac{16 \text{ ADC Clock Cycles}}{\text{ADC Clock Frequency}}$$

$$\text{Number of Bus Cycles} = \text{Conversion Time} \times \text{Bus Frequency}$$

3.3.4 Continuous Conversion

In the continuous conversion mode (ADCO = 1), the ADC continuously converts the selected channel filling the ADC data register (ADR) with new data after each conversion. Data from the previous conversion will be overwritten whether that data has been read or not. Conversions will continue until the ADCO bit is cleared. The COCO bit (ADSCR, \$003C) is set after each conversion and will stay set until the next read of the ADC data register.

When a conversion is in process and the ADSCR is written, the current conversion data should be discarded to prevent an incorrect reading.

3.3.5 Accuracy and Precision

The conversion process is monotonic and has no missing codes.

3.4 Interrupts

When the AIEN bit is set, the ADC module is capable of generating a central processor unit (CPU) interrupt after each ADC conversion. A CPU interrupt is generated if the COCO bit is at 0. The COCO bit is not used as a conversion complete flag when interrupts are enabled.

3.5 Low-Power Modes

The following subsections describe the ADC in low-power modes.

3.5.1 Wait Mode

The ADC continues normal operation during wait mode. Any enabled CPU interrupt request from the ADC can bring the microcontroller unit (MCU) out of wait mode. If the ADC is not required to bring the MCU out of wait mode, power down the ADC by setting the CH[4:0] bits in ADSCR to 1s before executing the WAIT instruction.

Central Processor Unit (CPU)

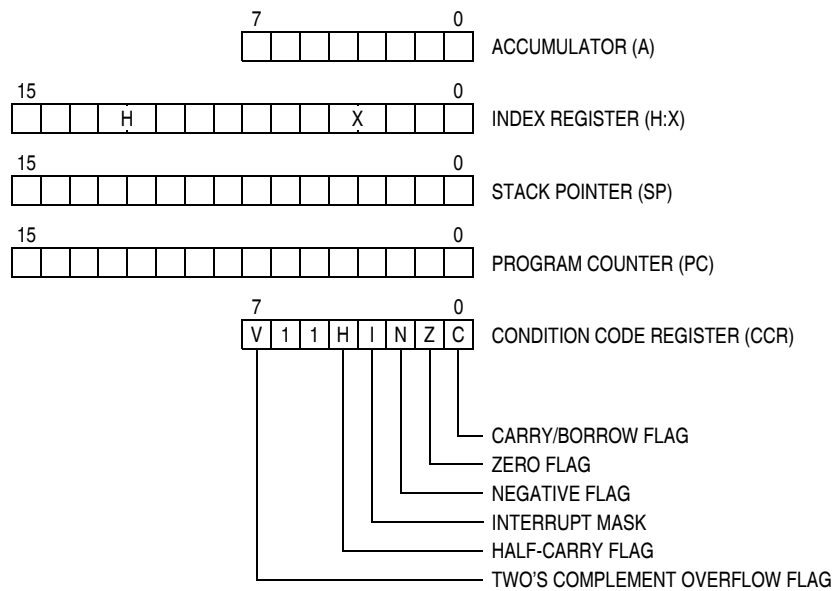


Figure 7-1. CPU Registers

7.3.1 Accumulator

The accumulator is a general-purpose 8-bit register. The CPU uses the accumulator to hold operands and the results of arithmetic/logic operations.

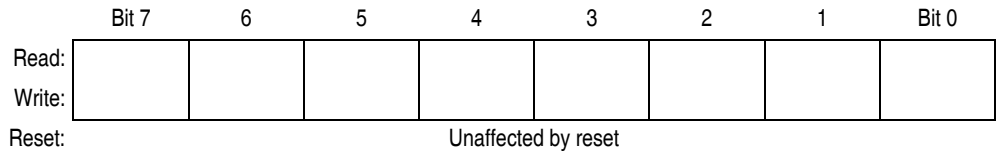


Figure 7-2. Accumulator (A)

7.3.2 Index Register

The 16-bit index register allows indexed addressing of a 64-Kbyte memory space. H is the upper byte of the index register, and X is the lower byte. H:X is the concatenated 16-bit index register.

In the indexed addressing modes, the CPU uses the contents of the index register to determine the conditional address of the operand.

The index register can serve also as a temporary data storage location.

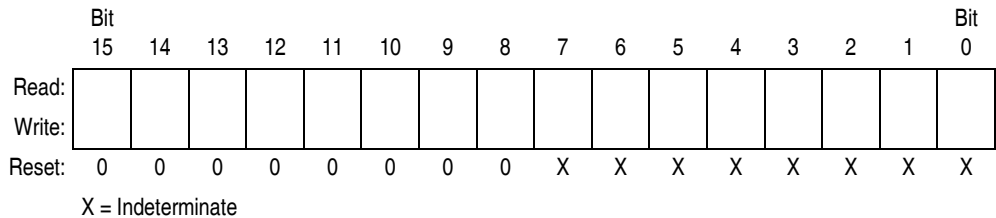


Figure 7-3. Index Register (H:X)

Table 7-1. Instruction Set Summary (Sheet 3 of 6)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
CLI	Clear Interrupt Mask	I ← 0	–	–	0	–	–	–	INH	9A		2
CLR <i>opr</i> CLRA CLR X CLR H CLR <i>opr</i> ,X CLR ,X CLR <i>opr</i> ,SP	Clear	M ← \$00 A ← \$00 X ← \$00 H ← \$00 M ← \$00 M ← \$00 M ← \$00	0	–	–	0	1	–	DIR INH INH INH IX1 IX SP1	3F 4F 5F 8C 6F 7F 9E6F	dd ff ff	3 1 1 1 3 2 4
CMP # <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> ,X CMP <i>opr</i> ,X CMP ,X CMP <i>opr</i> ,SP CMP <i>opr</i> ,SP	Compare A with M	(A) – (M)	†	–	–	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A1 B1 C1 D1 E1 F1 9EE1 9ED1	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
COM <i>opr</i> COMA COM X COM <i>opr</i> ,X COM ,X COM <i>opr</i> ,SP	Complement (One's Complement)	M ← (M̄) = \$FF – (M) A ← (Ā) = \$FF – (M) X ← (X̄) = \$FF – (M) M ← (M̄) = \$FF – (M) M ← (M̄) = \$FF – (M) M ← (M̄) = \$FF – (M)	0	–	–	†	†	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd ff ff	4 1 1 4 3 5
CPHX # <i>opr</i> CPHX <i>opr</i>	Compare H:X with M	(H:X) – (M:M + 1)	†	–	–	†	†	†	IMM DIR	65 75	ii ii+1 dd	3 4
CPX # <i>opr</i> CPX <i>opr</i> CPX <i>opr</i> CPX ,X CPX <i>opr</i> ,X CPX <i>opr</i> ,X CPX <i>opr</i> ,SP CPX <i>opr</i> ,SP	Compare X with M	(X) – (M)	†	–	–	†	†	†	IMM DIR EXT IX2 IX1 IX SP1 SP2	A3 B3 C3 D3 E3 F3 9EE3 9ED3	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
DAA	Decimal Adjust A	(A) ₁₀	U	–	–	†	†	†	INH	72		2
DBNZ <i>opr</i> , <i>rel</i> DBNZ A, <i>rel</i> DBNZ X, <i>rel</i> DBNZ <i>opr</i> ,X, <i>rel</i> DBNZ X, <i>rel</i> DBNZ <i>opr</i> ,SP, <i>rel</i>	Decrement and Branch if Not Zero	A ← (A) – 1 or M ← (M) – 1 or X ← (X) – 1 PC ← (PC) + 3 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 3 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 2 + <i>rel</i> ? (result) ≠ 0 PC ← (PC) + 4 + <i>rel</i> ? (result) ≠ 0	–	–	–	–	–	–	DIR INH INH IX1 IX SP1	3B 4B 5B 6B 7B 9E6B	dd rr rr rr ff rr rr ff rr	5 3 3 5 4 6
DEC <i>opr</i> DECA DEC X DEC <i>opr</i> ,X DEC ,X DEC <i>opr</i> ,SP	Decrement	M ← (M) – 1 A ← (A) – 1 X ← (X) – 1 M ← (M) – 1 M ← (M) – 1 M ← (M) – 1	†	–	–	†	†	–	DIR INH INH IX1 IX SP1	3A 4A 5A 6A 7A 9E6A	dd ff ff	4 1 1 4 3 5
DIV	Divide	A ← (H:A)/(X) H ← Remainder	–	–	–	–	†	†	INH	52		7
EOR # <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> ,X EOR <i>opr</i> ,X EOR ,X EOR <i>opr</i> ,SP EOR <i>opr</i> ,SP	Exclusive OR M with A	A ← (A ⊕ M)	0	–	–	†	†	–	IMM DIR EXT IX2 IX1 IX SP1 SP2	A8 B8 C8 D8 E8 F8 9EE8 9ED8	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
INC <i>opr</i> INCA INC X INC <i>opr</i> ,X INC ,X INC <i>opr</i> ,SP	Increment	M ← (M) + 1 A ← (A) + 1 X ← (X) + 1 M ← (M) + 1 M ← (M) + 1 M ← (M) + 1	†	–	–	†	†	–	DIR INH INH IX1 IX SP1	3C 4C 5C 6C 7C 9E6C	dd ff ff	4 1 1 4 3 5

Chapter 8

External Interrupt (IRQ)

8.1 Introduction

The $\overline{\text{IRQ}}$ pin (external interrupt), shared with PTA2 (general purpose input) and keyboard interrupt (KBI), provides a maskable interrupt input

8.2 Features

Features of the IRQ module include the following:

- External interrupt pin, $\overline{\text{IRQ}}$
- $\overline{\text{IRQ}}$ interrupt control bits
- Programmable edge-only or edge and level interrupt sensitivity
- Automatic interrupt acknowledge
- Selectable internal pullup resistor

8.3 Functional Description

$\overline{\text{IRQ}}$ pin functionality is enabled by setting configuration register 2 (CONFIG2) IRQEN bit accordingly. A zero disables the IRQ function and PTA2 will assume the other shared functionalities. A one enables the IRQ function.

A low level applied to the external interrupt request ($\overline{\text{IRQ}}$) pin can latch a CPU interrupt request.

[Figure 8-2](#) shows the structure of the IRQ module.

Interrupt signals on the $\overline{\text{IRQ}}$ pin are latched into the IRQ latch. The IRQ latch remains set until one of the following actions occurs:

- IRQ vector fetch — An IRQ vector fetch automatically generates an interrupt acknowledge signal that clears the IRQ latch.
- Software clear — Software can clear the IRQ latch by writing a 1 to the ACK bit in the interrupt status and control register (INTSCR).
- Reset — A reset automatically clears the IRQ latch.

The external interrupt pin is falling-edge-triggered out of reset and is software-configurable to be either falling-edge or falling-edge and low-level triggered. The MODE bit in INTSCR controls the triggering sensitivity of the $\overline{\text{IRQ}}$ pin.

8.7.1 IRQ Input Pins ($\overline{\text{IRQ}}$)

The $\overline{\text{IRQ}}$ pin provides a maskable external interrupt source. The $\overline{\text{IRQ}}$ pin contains an internal pullup device.

8.8 Registers

The IRQ status and control register (INTSCR) controls and monitors operation of the IRQ module. See [Chapter 5 Configuration Register \(CONFIG\)](#).

The INTSCR has the following functions:

- Shows the state of the IRQ flag
- Clears the IRQ latch
- Masks the IRQ interrupt request
- Controls triggering sensitivity of the $\overline{\text{IRQ}}$ interrupt pin

Address: \$001D

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	IRQF	0	IMASK	MODE
Write:						ACK		
Reset:	0	0	0	0	0	0	0	0

 = Unimplemented

Figure 8-3. IRQ Status and Control Register (INTSCR)

IRQF — IRQ Flag

This read-only status bit is set when the IRQ interrupt is pending.

1 = $\overline{\text{IRQ}}$ interrupt pending

0 = $\overline{\text{IRQ}}$ interrupt not pending

ACK — IRQ Interrupt Request Acknowledge Bit

Writing a 1 to this write-only bit clears the IRQ latch. ACK always reads as 0.

IMASK — IRQ Interrupt Mask Bit

Writing a 1 to this read/write bit disables the IRQ interrupt request.

1 = IRQ interrupt request disabled

0 = IRQ interrupt request enabled

MODE — IRQ Edge/Level Select Bit

This read/write bit controls the triggering sensitivity of the $\overline{\text{IRQ}}$ pin.

1 = $\overline{\text{IRQ}}$ interrupt request on falling edges and low levels

0 = $\overline{\text{IRQ}}$ interrupt request on falling edges only

13.4.1 External Pin Reset

The $\overline{\text{RST}}$ pin circuits include an internal pullup device. Pulling the asynchronous $\overline{\text{RST}}$ pin low halts all processing. The PIN bit of the SIM reset status register (SRSR) is set as long as $\overline{\text{RST}}$ is held low for at least the minimum t_{RL} time. Figure 13-3 shows the relative timing. The $\overline{\text{RST}}$ pin function is only available if the RSTEN bit is set in the CONFIG2 register.

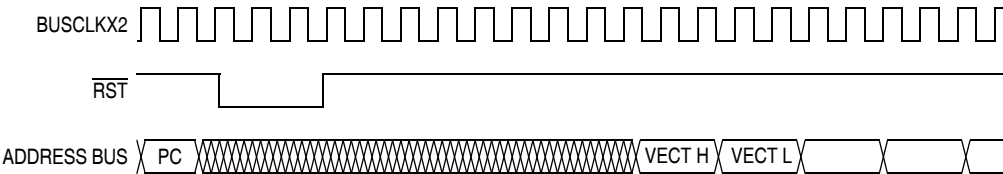


Figure 13-3. External Reset Timing

13.4.2 Active Resets from Internal Sources

The $\overline{\text{RST}}$ pin is initially setup as a general-purpose input after a POR. Setting the RSTEN bit in the CONFIG2 register enables the pin for the reset function. This section assumes the RSTEN bit is set when describing activity on the $\overline{\text{RST}}$ pin.

NOTE

For POR and LVI resets, the SIM cycles through 4096 BUSCLKX4 cycles during which the SIM forces the $\overline{\text{RST}}$ pin low. The internal reset signal then follows the sequence from the falling edge of $\overline{\text{RST}}$ shown in Figure 13-4.

The COP reset is asynchronous to the bus clock.

The active reset feature allows the part to issue a reset to peripherals and other chips within a system built around the MCU.

All internal reset sources actively pull the $\overline{\text{RST}}$ pin low for 32 BUSCLKX4 cycles to allow resetting of external peripherals. The internal reset signal IRST continues to be asserted for an additional 32 cycles (see Figure 13-4). An internal reset can be caused by an illegal address, illegal opcode, COP time out, LVI, or POR (see Figure 13-5).

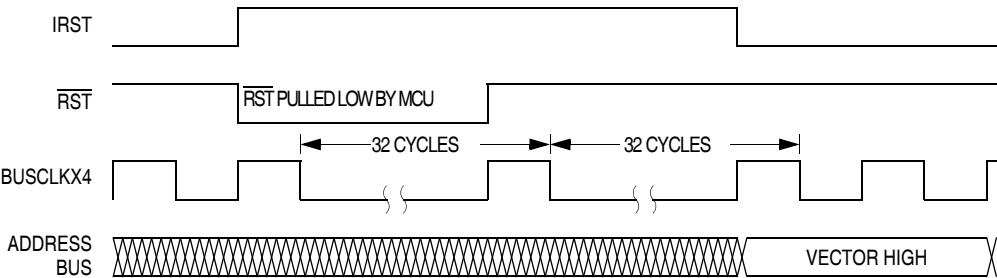


Figure 13-4. Internal Reset Timing

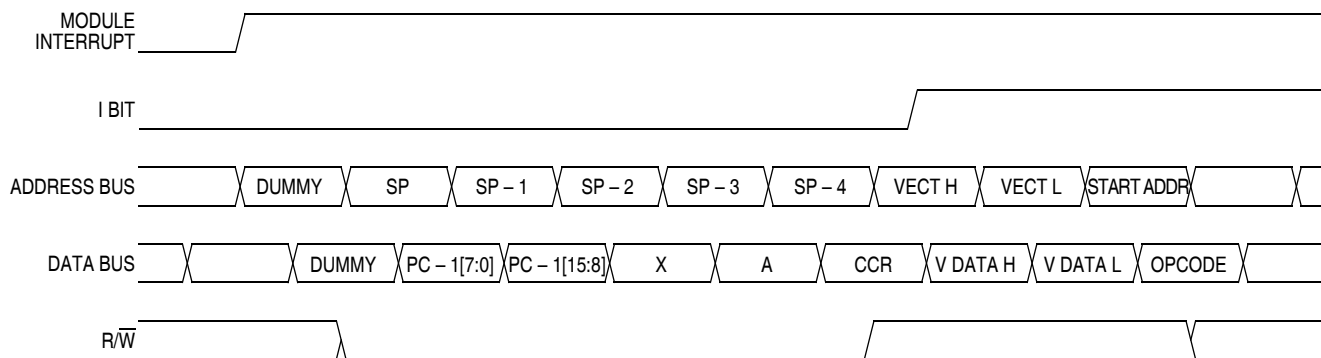


Figure 13-8. Interrupt Entry

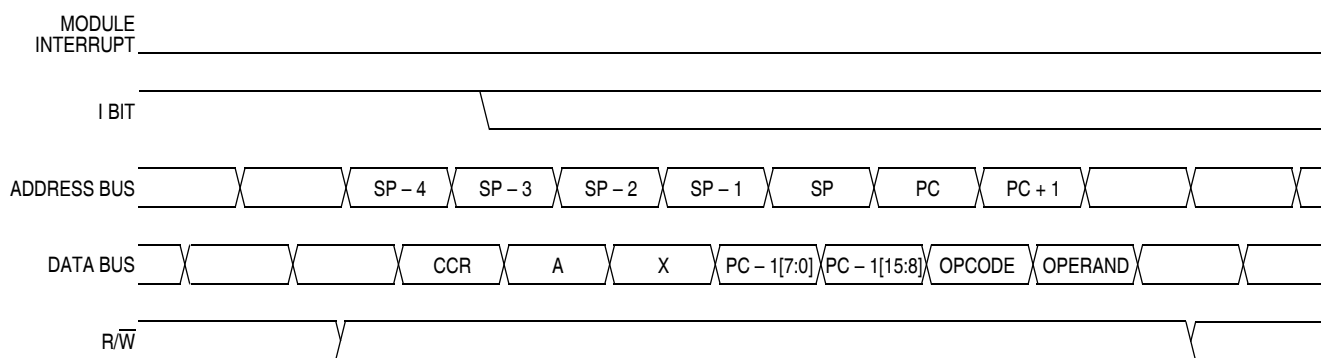


Figure 13-9. Interrupt Recovery

13.6.1.1 Hardware Interrupts

A hardware interrupt does not stop the current instruction. Processing of a hardware interrupt begins after completion of the current instruction. When the current instruction is complete, the SIM checks all pending hardware interrupts. If interrupts are not masked (I bit clear in the condition code register), and if the corresponding interrupt enable bit is set, the SIM proceeds with interrupt processing; otherwise, the next instruction is fetched and executed.

If more than one interrupt is pending at the end of an instruction execution, the highest priority interrupt is serviced first. [Figure 13-10](#) demonstrates what happens when two interrupts are pending. If an interrupt is pending upon exit from the original interrupt service routine, the pending interrupt is serviced before the LDA instruction is executed.

The LDA opcode is prefetched by both the INT1 and INT2 return-from-interrupt (RTI) instructions. However, in the case of the INT1 RTI prefetch, this is a redundant operation.

NOTE

To maintain compatibility with the M6805 Family, the H register is not pushed on the stack during interrupt entry. If the interrupt service routine modifies the H register or uses the indexed addressing mode, software should save the H register and then restore it prior to exiting the routine.

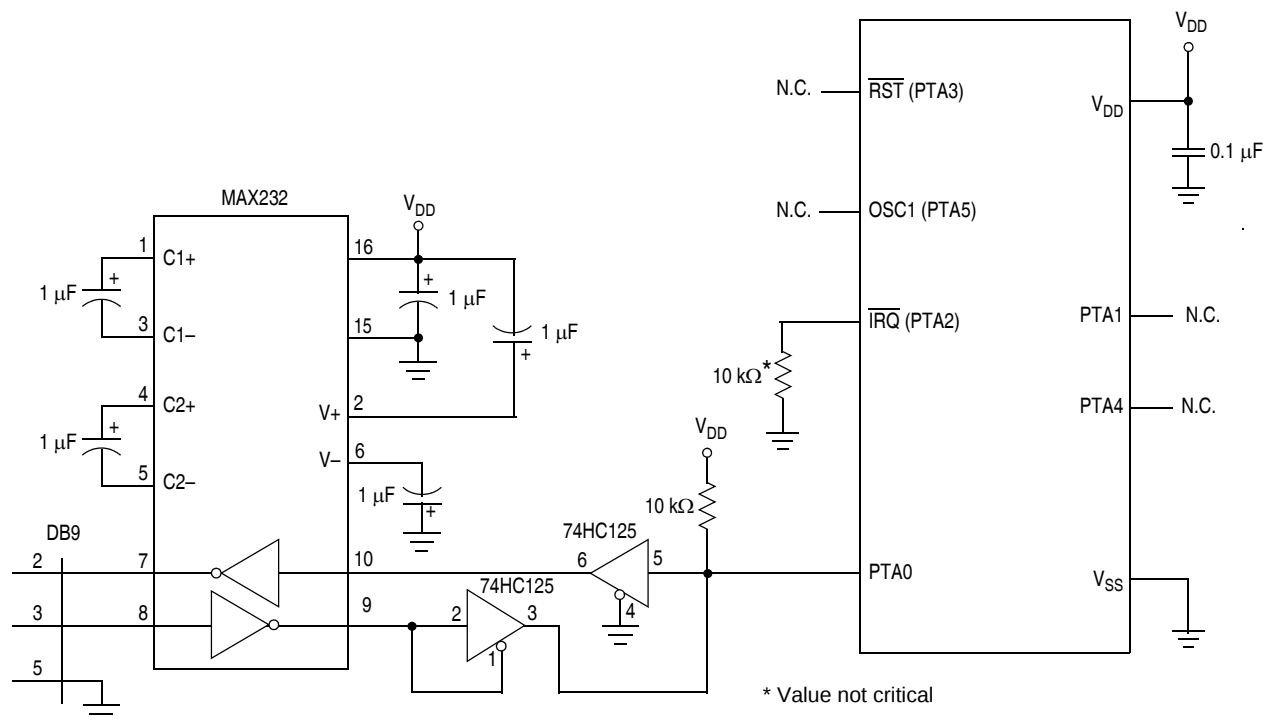


Figure 15-12. Monitor Mode Circuit (Internal Clock, No High Voltage)

Simple monitor commands can access any memory address. In monitor mode, the MCU can execute code downloaded into RAM by a host computer while most MCU pins retain normal operating mode functions. All communication between the host computer and the MCU is through the PTA0 pin. A level-shifting and multiplexing interface is required between PTA0 and the host computer. PTA0 is used in a wired-OR configuration and requires a pullup resistor.

The monitor code has been updated from previous versions of the monitor code to allow enabling the internal oscillator to generate the internal clock. This addition, which is enabled when $\overline{\text{IRQ}}$ is held low out of reset, is intended to support serial communication/programming at 9600 baud in monitor mode by using the internal oscillator, and the internal oscillator user trim value OSCTRIM (FLASH location \$FFC0, if programmed) to generate the desired internal frequency (3.2 MHz). Since this feature is enabled only when $\overline{\text{IRQ}}$ is held low out of reset, it cannot be used when the reset vector is programmed (i.e., the value is not \$FFFF) because entry into monitor mode in this case requires V_{TST} on $\overline{\text{IRQ}}$. The $\overline{\text{IRQ}}$ pin must remain low during this monitor session in order to maintain communication.

Table 15-1 shows the pin conditions for entering monitor mode. As specified in the table, monitor mode may be entered after a power-on reset (POR) and will allow communication at 9600 baud provided one of the following sets of conditions is met:

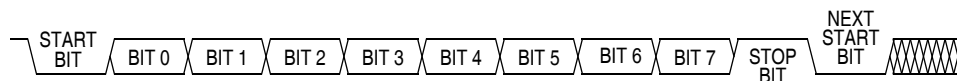
- If \$FFFE and \$FFFF do not contain \$FF (programmed state):
 - The external clock is 9.8304 MHz
 - $\overline{\text{IRQ}} = V_{\text{TST}}$
- If \$FFFE and \$FFFF contain \$FF (erased state):
 - The external clock is 9.8304 MHz
 - $\overline{\text{IRQ}} = V_{\text{DD}}$ (this can be implemented through the internal $\overline{\text{IRQ}}$ pullup)
- If \$FFFE and \$FFFF contain \$FF (erased state):
 - $\overline{\text{IRQ}} = V_{\text{SS}}$ (internal oscillator is selected, no external clock required)

Table 15-2. Mode Difference

Modes	Functions					
	Reset Vector High	Reset Vector Low	Break Vector High	Break Vector Low	SWI Vector High	SWI Vector Low
User	\$FFFE	\$FFFF	\$FFFC	\$FFFD	\$FFFC	\$FFFD
Monitor	\$FEFE	\$FEFF	\$FEFC	\$FEFD	\$FEFC	\$FEFD

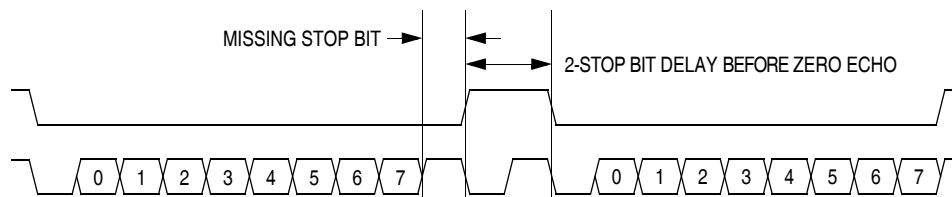
15.3.1.4 Data Format

Communication with the monitor ROM is in standard non-return-to-zero (NRZ) mark/space data format. Transmit and receive baud rates must be identical.


Figure 15-13. Monitor Data Format

15.3.1.5 Break Signal

A start bit (logic 0) followed by nine logic 0 bits is a break signal. When the monitor receives a break signal, it drives the PTA0 pin high for the duration of two bits and then echoes back the break signal.


Figure 15-14. Break Transaction

15.3.1.6 Baud Rate

The monitor communication baud rate is controlled by the frequency of the external or internal oscillator and the state of the appropriate pins as shown in [Table 15-1](#).

[Table 15-1](#) also lists the bus frequencies to achieve standard baud rates. The effective baud rate is the bus frequency divided by 256 when using an external oscillator. When using the internal oscillator in forced monitor mode, the effective baud rate is the bus frequency divided by 335.

15.3.1.7 Commands

The monitor ROM firmware uses these commands:

- READ (read memory)
- WRITE (write memory)
- IREAD (indexed read)
- IWRITE (indexed write)
- READSP (read stack pointer)
- RUN (run user program)

16.3 Functional Operating Range

Characteristic	Symbol	Value	Unit	Temp. Code
Operating temperature range	T_A	–40 to +125 –40 to +105 –40 to +85	•C	M V C
Operating voltage range	V_{DD}	2.7 to 5.5	V	—

16.4 Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal resistance			
8-pin PDIP		105	
8-pin SOIC		142	
8-pin DFN		173	
16-pin PDIP		76	
16-pin SOIC		90	
16-pin TSSOP		133	
I/O pin power dissipation	$P_{I/O}$	User determined	W
Power dissipation ⁽¹⁾	P_D	$P_D = (I_{DD} \times V_{DD})$ $+ P_{I/O} = K/(T_J + 273 \cdot C)$	W
Constant ⁽²⁾	K	$P_D \times (T_A + 273 \cdot C)$ $+ P_D^2 \times \theta_{JA}$	W/•C
Average junction temperature	T_J	$T_A + (P_D \times \theta_{JA})$	•C
Maximum junction temperature	T_{JM}	150	•C

1. Power dissipation is a function of temperature.

2. K constant unique to the device. K can be determined for a known T_A and measured P_D . With this value of K, P_D and T_J can be determined for any value of T_A .

16.11 3-V Control Timing

Characteristic ⁽¹⁾	Symbol	Min	Max	Unit
Internal operating frequency	f_{OP} (f_{BUS})	—	4	MHz
Internal clock period ($1/f_{OP}$)	t_{cyc}	250	—	ns
$\overline{RST}$ input pulse width low	t_{RL}	200	—	ns
$\overline{IRQ}$ interrupt pulse width low (edge-triggered)	t_{ILIH}	200	—	ns
$\overline{IRQ}$ interrupt pulse period	t_{ILIL}	Note ⁽²⁾	—	t_{cyc}

- $V_{DD} = 2.7$ to 3.3 Vdc, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H ; timing shown with respect to 20% V_{DD} and 70% V_{DD} , unless otherwise noted.
- The minimum period is the number of cycles it takes to execute the interrupt service routine plus 1 t_{cyc} .

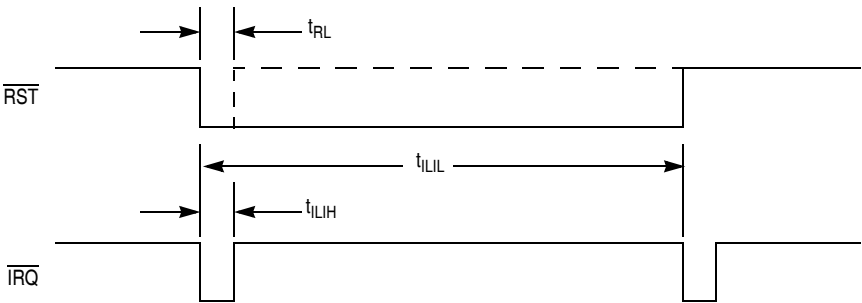


Figure 16-7. $\overline{RST}$ and $\overline{IRQ}$ Timing

16.13 Supply Current Characteristics

Characteristic ⁽¹⁾	Voltage	Bus Frequency (MHz)	Symbol	Typ ⁽²⁾	Max	Unit
Run Mode V_{DD} supply current ⁽³⁾	5.0 3.0	3.2 3.2	$R_{I_{DD}}$	6.0 2.5	7.0 3.2	mA
Wait Mode V_{DD} supply current ⁽⁴⁾	5.0 3.0	3.2 3.2	$W_{I_{DD}}$	1.0 0.67	1.5 1.0	mA mA
Stop Mode V_{DD} supply current ⁽⁵⁾ –40 to 85°C –40 to 105°C –40 to 125°C 25°C with auto wakeup enabled Incremental current with LVI enabled at 25°C	5.0		$S_{I_{DD}}$	0.04 — — 7 125	1.0 2.0 5.0 — —	μA
Stop Mode V_{DD} supply current ⁽⁵⁾ –40 to 85°C –40 to 105°C –40 to 125°C 25°C with auto wakeup enabled Incremental current with LVI enabled at 25°C	3.0		$S_{I_{DD}}$	0.02 — — 5 100	0.5 1.0 4.0 — —	μA

1. $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H , unless otherwise noted.

2. Typical values reflect average measurements at 25°C only.

3. Run (operating) I_{DD} measured using trimmed internal oscillator, ADC off, all other modules enabled. All pins configured as inputs and tied to 0.2 V from rail.

4. Wait I_{DD} measured using trimmed internal oscillator, ADC off, all other modules enabled. All pins configured as inputs and tied to 0.2 V from rail.

5. Stop I_{DD} measured with all pins tied to 0.2 V or less from rail. No dc loads. On the 8-pin versions, port B is configured as inputs with pullups enabled.



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. 626-03 TO 626-06 OBSOLETE. NEW STANDARD 626-07.

△ 4. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.

△ 5. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CONERS).

STYLE 1:

PIN	1.	AC IN	5.	GROUND
	2.	DC + IN	6.	OUTPUT
	3.	DC – IN	7.	AUXILIARY
	4.	AC IN	8.	VCC

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TITLE: 8 LD PDIP			DOCUMENT NO: 98ASB42420B		REV: N
			CASE NUMBER: 626-06		19 MAY 2005
			STANDARD: NON-JEDEC		

